LEE & STERBA, P.C.
ATTORNEYS AND COUNSELORS AT LAW

1101 Wilson Boulevard
SUITE 2000
ARLINGTON, VIRGINIA 22209

Telephone 703.525.0978
FACSIMILE 703.525.4265
www.lee-iplaw.com

► FACSIMILE TRANSMITTAL SHEET ◄

TO: TECHNOLOGY CENTER **2823**   DATE: AUGUST 21, 2003

AFTER FINAL

COMPANY: **U.S. PATENT AND TRADEMARK OFFICE**

FROM: **EUGENE M. LEE, REG. NO. 32,039**

FAX NUMBER: **703.872-9319**   TOTAL NO. OF PAGES INCLUDING COVER: **8**

PHONE NUMBER: YOUR REFERENCE NUMBER:

CC: OUR REFERENCE NUMBER:

RE: **U.S. PATENT APPLICATION SERIAL NO. 09/686,624**

Transmitted herewith is:

AMENDMENT AFTER FINAL PURSUANT TO 37 C.F.R. §1.116

in connection with application Serial No. 09/686,624 pending in Art Unit 2823 before Examiner Khiem D. Nguyen.

Return receipt , via facsimile [to 703.525.4265], of the above-referenced document(s) is hereby requested.

THE INFORMATION CONTAINED IN THIS FACSIMILE IS INTENDED FOR THE NAMED RECIPIENTS ONLY. IT MAY CONTAIN PRIVILEGED AND CONFIDENTIAL INFORMATION. AND IF YOU ARE NOT AN INTENDED RECIPIENT, YOU MUST NOT COPY, DISTRIBUTE OR TAKE ANY ACTION IN RELIANCE ON IT. IF YOU HAVE RECEIVED THIS FACSIMILE IN ERROR, PLEASE NOTIFY US IMMEDIATELY BY FACSIMILE OR BY CALLING (703) 525-0978 OR BY E-MAIL (info@lee-iplaw.com), AND RETURN THE ORIGINAL TO US BY MAIL. WE WILL REIMBURSE YOU FOR THE POSTAGE.

LEE & STERBA, P.C.

AFTER FINAL

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	)	
	)	
Jung-Ho Lee, *et al.*	)	Examiner: Khiem D. Nguyen
	)	
Serial No.: 09/686,624	)	Group Art Unit: 2823
	)	
Filed: October 12, 2000	)	Attorney Docket No.: 253/006
	)	
For: SPIN-ON GLASS COMPOSITION AND	)	
METHOD OF FORMING SILICON	)	
OXIDE LAYER IN SEMICONDUCTOR	)	
MANUFACTURING PROCESS	)	
USING THE SAME	)	

Commissioner for Patents
United States Patent and Trademark Office
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT AFTER FINAL
PURSUANT TO 37 C.F.R. § 1.116

Sir:

INTRODUCTORY COMMENT

In response to the Office Action mailed May 21, 2003, and made final, kindly

amend the above-identified application as follows: